



**ADVANCED SIGNAL
INTEGRITY FOR
HIGH-SPEED DIGITAL
DESIGNS**

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STEPHEN H. HALL

HOWARD L. HECK



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CONTENTS

Preface	xv
1. Introduction: The Importance of Signal Integrity	1
1.1 Computing Power: Past and Future, 1	
1.2 The Problem, 4	
1.3 The Basics, 5	
1.4 A New Realm of Bus Design, 7	
1.5 Scope of the Book, 7	
1.6 Summary, 8	
References, 8	
2. Electromagnetic Fundamentals for Signal Integrity	9
2.1 Maxwell's Equations, 10	
2.2 Common Vector Operators, 13	
2.2.1 Vector, 13	
2.2.2 Dot Product, 13	
2.2.3 Cross Product, 14	
2.2.4 Vector and Scalar Fields, 15	
2.2.5 Flux, 15	
2.2.6 Gradient, 18	
2.2.7 Divergence, 18	
2.2.8 Curl, 20	
2.3 Wave Propagation, 23	
2.3.1 Wave Equation, 23	
2.3.2 Relation Between E and H and the Transverse Electromagnetic Mode, 25	
2.3.3 Time-Harmonic Fields, 27	

2.3.4	Propagation of Time-Harmonic Plane Waves, 28
2.4	Electrostatics, 32
2.4.1	Electrostatic Scalar Potential in Terms of an Electric Field, 36
2.4.2	Energy in an Electric Field, 37
2.4.3	Capacitance, 40
2.4.4	Energy Stored in a Capacitor, 41
2.5	Magnetostatics, 42
2.5.1	Magnetic Vector Potential, 46
2.5.2	Inductance, 48
2.5.3	Energy in a Magnetic Field, 51
2.6	Power Flow and the Poynting Vector, 53
2.6.1	Time-Averaged Values, 56
2.7	Reflections of Electromagnetic Waves, 57
2.7.1	Plane Wave Incident on a Perfect Conductor, 57
2.7.2	Plane Wave Incident on a Lossless Dielectric, 60
	References, 62
	Problems, 62

3. Ideal Transmission-Line Fundamentals

65

3.1	Transmission-Line Structures, 66
3.2	Wave Propagation on Loss-Free Transmission Lines, 67
3.2.1	Electric and Magnetic Fields on a Transmission Line, 68
3.2.2	Telegrapher's Equations, 73
3.2.3	Equivalent Circuit for the Loss-Free Case, 76
3.2.4	Wave Equation in Terms of LC , 80
3.3	Transmission-Line Properties, 82
3.3.1	Transmission-Line Phase Velocity, 82
3.3.2	Transmission-Line Characteristic Impedance, 82
3.3.3	Effective Dielectric Permittivity, 83
3.3.4	Simple Formulas for Calculating the Characteristic Impedance, 85
3.3.5	Validity of the TEM Approximation, 86
3.4	Transmission-Line Parameters for the Loss-Free Case, 90
3.4.1	Laplace and Poisson Equations, 91
3.4.2	Transmission-Line Parameters for a Coaxial Line, 91
3.4.3	Transmission-Line Parameters for a Microstrip, 94
3.4.4	Charge Distribution Near a Conductor Edge, 100
3.4.5	Charge Distribution and Transmission-Line Parameters, 104

- 3.4.6 Field Mapping, 107
- 3.5 Transmission-Line Reflections, 113
 - 3.5.1 Transmission-Line Reflection and Transmission Coefficient, 113
 - 3.5.2 Launching an Initial Wave, 116
 - 3.5.3 Multiple Reflections, 116
 - 3.5.4 Lattice Diagrams and Over- or Underdriven Transmission Lines, 118
 - 3.5.5 Lattice Diagrams for Nonideal Topologies, 121
 - 3.5.6 Effect of Rise and Fall Times on Reflections, 129
 - 3.5.7 Reflections from Reactive Loads, 129
- 3.6 Time-Domain Reflectometry, 134
 - 3.6.1 Measuring the Characteristic Impedance and Delay of a Transmission Line, 134
 - 3.6.2 Measuring Inductance and Capacitance of Reactive Structures, 137
 - 3.6.3 Understanding the TDR Profile, 140
- References, 140
- Problems, 141

4. Crosstalk

145

- 4.1 Mutual Inductance and Capacitance, 146
 - 4.1.1 Mutual Inductance, 147
 - 4.1.2 Mutual Capacitance, 149
 - 4.1.3 Field Solvers, 152
- 4.2 Coupled Wave Equations, 153
 - 4.2.1 Wave Equation Revisited, 153
 - 4.2.2 Coupled Wave Equations, 155
- 4.3 Coupled Line Analysis, 157
 - 4.3.1 Impedance and Velocity, 157
 - 4.3.2 Coupled Noise, 165
- 4.4 Modal Analysis, 177
 - 4.4.1 Modal Decomposition, 178
 - 4.4.2 Modal Impedance and Velocity, 180
 - 4.4.3 Reconstructing the Signal, 180
 - 4.4.4 Modal Analysis, 181
 - 4.4.5 Modal Analysis of Lossy Lines, 192
- 4.5 Crosstalk Minimization, 193
- 4.6 Summary, 194
- References, 195
- Problems, 195

5. Nonideal Conductor Models	201
5.1 Signals Propagating in Unbounded Conductive Media, 202	
5.1.1 Propagation Constant for Conductive Media, 202	
5.1.2 Skin Depth, 204	
5.2 Classic Conductor Model for Transmission Lines, 205	
5.2.1 Dc Losses in Conductors, 206	
5.2.2 Frequency-Dependent Resistance in Conductors, 207	
5.2.3 Frequency-Dependent Inductance, 213	
5.2.4 Power Loss in a Smooth Conductor, 218	
5.3 Surface Roughness, 222	
5.3.1 Hammerstad Model, 223	
5.3.2 Hemispherical Model, 228	
5.3.3 Huray Model, 237	
5.3.4 Conclusions, 243	
5.4 Transmission-Line Parameters for Nonideal Conductors, 244	
5.4.1 Equivalent Circuit, Impedance, and Propagation Constant, 244	
5.4.2 Telegrapher's Equations for a Real Conductor and a Perfect Dielectric, 246	
References, 247	
Problems, 247	
6. Electrical Properties of Dielectrics	249
6.1 Polarization of Dielectrics, 250	
6.1.1 Electronic Polarization, 250	
6.1.2 Orientational (Dipole) Polarization, 253	
6.1.3 Ionic (Molecular) Polarization, 253	
6.1.4 Relative Permittivity, 254	
6.2 Classification of Dielectric Materials, 256	
6.3 Frequency-Dependent Dielectric Behavior, 256	
6.3.1 Dc Dielectric Losses, 257	
6.3.2 Frequency-Dependent Dielectric Model: Single Pole, 257	
6.3.3 Anomalous Dispersion, 261	
6.3.4 Frequency-Dependent Dielectric Model: Multipole, 262	
6.3.5 Infinite-Pole Model, 266	
6.4 Properties of a Physical Dielectric Model, 269	
6.4.1 Relationship Between ϵ' and ϵ'' , 269	
6.4.2 Mathematical Limits, 271	

6.5 Fiber-Weave Effect, 274	
6.5.1 Physical Structure of an FR4 Dielectric and Dielectric Constant Variation, 275	
6.5.2 Mitigation, 276	
6.5.3 Modeling the Fiber-Weave Effect, 277	
6.6 Environmental Variation in Dielectric Behavior, 279	
6.6.1 Environmental Effects on Transmission-Line Performance, 281	
6.6.2 Mitigation, 283	
6.6.3 Modeling the Effect of Relative Humidity on an FR4 Dielectric, 284	
6.7 Transmission-Line Parameters for Lossy Dielectrics and Realistic Conductors, 285	
6.7.1 Equivalent Circuit, Impedance, and Propagation Constant, 285	
6.7.2 Telegrapher's Equations for Realistic Conductors and Lossy Dielectrics, 291	
References, 292	
Problems, 292	
7. Differential Signaling	297
7.1 Removal of Common-Mode Noise, 299	
7.2 Differential Crosstalk, 300	
7.3 Virtual Reference Plane, 302	
7.4 Propagation of Modal Voltages, 303	
7.5 Common Terminology, 304	
7.6 Drawbacks of Differential Signaling, 305	
7.6.1 Mode Conversion, 305	
7.6.2 Fiber-Weave Effect, 310	
Reference, 313	
Problems, 313	
8. Mathematical Requirements for Physical Channels	315
8.1 Frequency-Domain Effects in Time-Domain Simulations, 316	
8.1.1 Linear and Time Invariance, 316	
8.1.2 Time- and Frequency-Domain Equivalencies, 317	
8.1.3 Frequency Spectrum of a Digital Pulse, 321	
8.1.4 System Response, 324	
8.1.5 Single-Bit (Pulse) Response, 327	
8.2 Requirements for a Physical Channel, 331	
8.2.1 Causality, 331	

- 8.2.2 Passivity, 340
- 8.2.3 Stability, 343
- References, 345
- Problems, 345

9. Network Analysis for Digital Engineers 347

- 9.1 High-Frequency Voltage and Current Waves, 349
 - 9.1.1 Input Reflection into a Terminated Network, 349
 - 9.1.2 Input Impedance, 353
- 9.2 Network Theory, 354
 - 9.2.1 Impedance Matrix, 355
 - 9.2.2 Scattering Matrix, 358
 - 9.2.3 *ABCD* Parameters, 382
 - 9.2.4 Cascading *S*-Parameters, 390
 - 9.2.5 Calibration and Deembedding, 395
 - 9.2.6 Changing the Reference Impedance, 399
 - 9.2.7 Multimode *S*-Parameters, 400
- 9.3 Properties of Physical *S*-Parameters, 406
 - 9.3.1 Passivity, 406
 - 9.3.2 Reality, 408
 - 9.3.3 Causality, 408
 - 9.3.4 Subjective Examination of *S*-Parameters, 410
- References, 413
- Problems, 413

10. Topics in High-Speed Channel Modeling 417

- 10.1 Creating a Physical Transmission-Line Model, 418
 - 10.1.1 Tabular Approach, 418
 - 10.1.2 Generating a Tabular Dielectric Model, 419
 - 10.1.3 Generating a Tabular Conductor Model, 420
- 10.2 NonIdeal Return Paths, 422
 - 10.2.1 Path of Least Impedance, 422
 - 10.2.2 Transmission Line Routed Over a Gap in the Reference Plane, 423
 - 10.2.3 Summary, 434
- 10.3 Vias, 434
 - 10.3.1 Via Resonance, 434
 - 10.3.2 Plane Radiation Losses, 437
 - 10.3.3 Parallel-Plate Waveguide, 439
- References, 441
- Problems, 442

11. I/O Circuits and Models	443
11.1 I/O Design Considerations, 444	
11.2 Push–Pull Transmitters, 446	
11.2.1 Operation, 446	
11.2.2 Linear Models, 448	
11.2.3 Nonlinear Models, 453	
11.2.4 Advanced Design Considerations, 455	
11.3 CMOS receivers, 459	
11.3.1 Operation, 459	
11.3.2 Modeling, 460	
11.3.3 Advanced Design Considerations, 460	
11.4 ESD Protection Circuits, 460	
11.4.1 Operation, 461	
11.4.2 Modeling, 461	
11.4.3 Advanced Design Considerations, 463	
11.5 On-Chip Termination, 463	
11.5.1 Operation, 463	
11.5.2 Modeling, 463	
11.5.3 Advanced Design Considerations, 464	
11.6 Bergeron Diagrams, 465	
11.6.1 Theory and Method, 470	
11.6.2 Limitations, 474	
11.7 Open-Drain Transmitters, 474	
11.7.1 Operation, 474	
11.7.2 Modeling, 476	
11.7.3 Advanced Design Considerations, 476	
11.8 Differential Current-Mode Transmitters, 479	
11.8.1 Operation, 479	
11.8.2 Modeling, 480	
11.8.3 Advanced Design Considerations, 480	
11.9 Low-Swing and Differential Receivers, 481	
11.9.1 Operation, 481	
11.9.2 Modeling, 482	
11.9.3 Advanced Design Considerations, 483	
11.10 IBIS Models, 483	
11.10.1 Model Structure and Development Process, 483	
11.10.2 Generating Model Data, 485	
11.10.3 Differential I/O Models, 488	
11.10.4 Example of an IBIS File, 490	
11.11 Summary, 492	
References, 492	

Problems, 494

12. Equalization **499**

- 12.1 Analysis and Design Background, 500
 - 12.1.1 Maximum Data Transfer Capacity, 500
 - 12.1.2 Linear Time-Invariant Systems, 502
 - 12.1.3 Ideal Versus Practical Interconnects, 506
 - 12.1.4 Equalization Overview, 511
- 12.2 Continuous-Time Linear Equalizers, 513
 - 12.2.1 Passive CTLEs, 514
 - 12.2.2 Active CTLEs, 521
- 12.3 Discrete Linear Equalizers, 522
 - 12.3.1 Transmitter Equalization, 525
 - 12.3.2 Coefficient Selection, 530
 - 12.3.3 Receiver Equalization, 535
 - 12.3.4 Nonidealities in DLEs, 536
 - 12.3.5 Adaptive Equalization, 536
- 12.4 Decision Feedback Equalization, 540
- 12.5 Summary, 542
- References, 545
- Problems, 546

13. Modeling and Budgeting of Timing Jitter and Noise **549**

- 13.1 Eye Diagram, 550
- 13.2 Bit Error Rate, 552
 - 13.2.1 Worst-Case Analysis, 552
 - 13.2.2 Bit Error Rate Analysis, 555
- 13.3 Jitter Sources and Budgets, 560
 - 13.3.1 Jitter Types and Sources, 561
 - 13.3.2 System Jitter Budgets, 568
- 13.4 Noise Sources and Budgets, 572
 - 13.4.1 Noise Sources, 572
 - 13.4.2 Noise Budgets, 579
- 13.5 Peak Distortion Analysis Methods, 583
 - 13.5.1 Superposition and the Pulse Response, 583
 - 13.5.2 Worst-Case Bit Patterns and Data Eyes, 585
 - 13.5.3 Peak Distortion Analysis Including Crosstalk, 594
 - 13.5.4 Limitations, 598
- 13.6 Summary, 599
- References, 599
- Problems, 600

14. System Analysis Using Response Surface Modeling	605
14.1 Model Design Considerations, 606	
14.2 Case Study: 10-Gb/s Differential PCB Interface, 607	
14.3 RSM Construction by Least Squares Fitting, 607	
14.4 Measures of Fit, 615	
14.4.1 Residuals, 615	
14.4.2 Fit Coefficients, 616	
14.5 Significance Testing, 618	
14.5.1 Model Significance: The F -Test, 618	
14.5.2 Parameter Significance: Individual t -Tests, 619	
14.6 Confidence Intervals, 621	
14.7 Sensitivity Analysis and Design Optimization, 623	
14.8 Defect Rate Prediction Using Monte Carlo Simulation, 628	
14.9 Additional RSM Considerations, 633	
14.10 Summary, 633	
References, 634	
Problems, 635	
Appendix A: Useful Formulas, Identities, Units, and Constants	637
Appendix B: Four-Port Conversions Between T- and S-Parameters	641
Appendix C: Critical Values of the F-Statistic	645
Appendix D: Critical Values of the T-Statistic	647
Appendix E: Causal Relationship Between Skin Effect Resistance and Internal Inductance for Rough Conductors	649
Appendix F: Spice Level 3 Model for 0.25 μm MOSIS Process	653
Index	655